Structure of package

ABSTRACT OF THE INVENTION

The present invention discloses a structure of wafer level packaging. The structure comprises a first patterned isolation layer, a conductive layer and a second patterned isolation layer. The first patterned isolation layer is formed with a passivation layer of an IC (Integrated Circuit). The conductive layer is configured to have a curved or winding conductive pattern. The second patterned isolation layer is formed over the conductive layer to have a plurality of openings, and contact metal balls can be formed on the openings to electrically couple to a print circuit board.

(Fig. 2)